ABSTRACT OF THE DISCLOSURE

An apparatus for testing an electronic component includes a substrate having a cavity on the upper surface for accommodating an electronic component. The electronic component is inserted into the cavity from a second electrode side. From under the cavity, a connecting conductor extends in a direction that is substantially perpendicular to the thickness direction of the substrate. The connecting conductor is electrically connected to a through-hole electrode. The upper end of the through-hole electrode is further connected to a terminal pad placed on the upper surface of the substrate. Characteristics of the electronic component are measured by attaching a first probe and a second probe to a first substrate of the electronic component and the terminal pad, respectively.